

Attorney Docket No. 10133101

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RECORDATION FORM COVER SHEET

To the Honorable Commissioner of Patents and Trademarks:
Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Chia-Chan HSU, Chun-Mu CHEN, Shan-Haw CHIOU

Additional name(s) of conveying parties attached?

☐ Yes ☒ No

2. Name and address of receiving party(ies)

Name: **Industrial Technology Research Institute**

Internal Address:

Street Address: **No. 195, Sec. 4, Chung Hsing Road, Chutung**City: **Hsinchu** State: Zip: **31040**Country: **TW**

Additional names(s) & address(es) attached?

☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of name☐ Other:Execution Date: **3/22/2012**

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the new application is:

A. Patent Application No.(s):

13/463,790

B. Patent No.(s):

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning this document should be mailed.

Name: **Quintero Law Office, PC**Street Address: **615 Hampton Drive, Suite A202**City: **Venice** State: **CA** Zip: **90291**6. Total number of applications and patents involved: **1**7. Total fee (37 C.F.R. 3.41): **\$40**

Enclosed

Authorized to be charged to credit card (Form PTO-2038 attached)

☒ Authorized to be charged to deposit account, if no fee attached.8. Deposit account number: **502447**

(Attach duplicate cover sheet if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Nelson A. Quintero, #52,143

Name of person signing

Signature

May 8, 2012

Date

Total number of pages including cover sheet, attachments, and documents: **2**

CH \$40.00 502447 13463790

ASSIGNMENT

WHEREAS, CHIA-CHAN HSU, Chun-Mu CHEN and Shan-Haw CHIOU hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

THERMOELECTRIC MATERIAL, METHOD FOR FABRICATING THE SAME, AND THERMOELECTRIC MODULE EMPLOYING THE SAME

Title: _____

Serial No. _____

Filed: _____

Executed on: March 22, 2012

WHEREAS, Industrial Technology Research Institute of No. 195, Sec. 4, Chung Hsiao Rd., Chung Hsiao, Hsinchu 31040, Taiwan, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN, Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Full name of sole or first inventor: CHIA-CHAN HSU

Inventor's signature: _____

Date: 2012/03/22

Full name of second inventor: CHUN-MU CHEN

Inventor's signature: Chun-mu Chen

Date: 2012/03/22

Full name of third inventor: SHAN-HAW CHIOU

Inventor's signature: Shan-Haw Chiu

Date: 2012/03/22